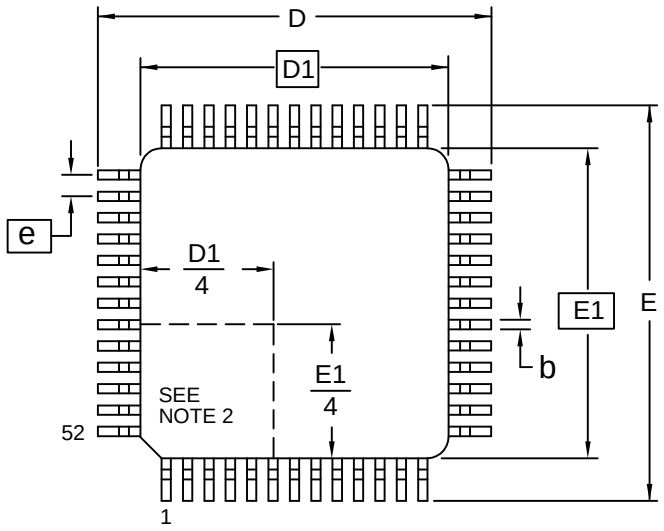
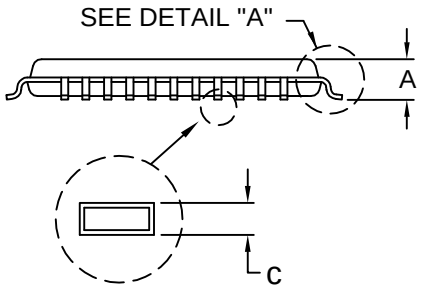
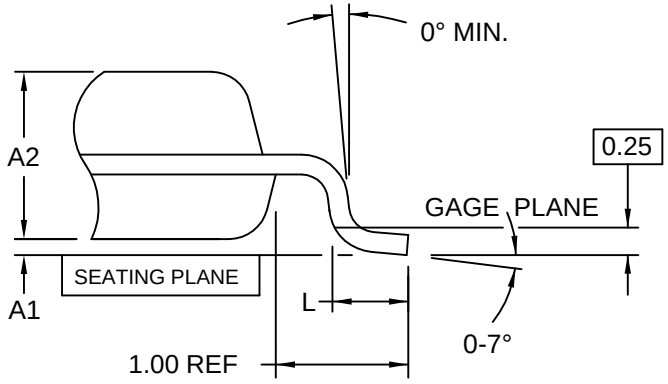


TOP VIEW

DIM	MIN	NOM	MAX
A	-	-	1.20
A1	0.05	0.10	0.15
A2	0.95	1.00	1.05
b	0.22	0.32	0.38
c	0.09	-	0.20
D	11.80	12.00	12.20
D1	10.00 BSC		
E	11.80	12.00	12.20
E1	10.00 BSC		
e	0.65 BSC		
L	0.45	0.60	0.75





DETAIL A

NOTES:
1. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH, BUT DO NOT INCLUDE MOLD PROTRUSION; ALLOWABLE PROTRUSION IS 0.254 MM ON D1 AND E1.
2. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
3. ALLOWABLE DAMBAR PROTRUSION IS 0.08 MM TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION. PROTRUSION NOT TO BE LOCATED ON LOWER RADIUS OR FOOT OF LEAD.
4. DIMENSIONS ARE IN MILLIMETERS.
5. MEETS JEDEC MS–206.

DALLAS SEMICONDUCTOR MAXIM

PROPRIETARY INFORMATION

TITLE: PACKAGE OUTLINE
52L TQFP, 10x10x1.0 MM

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0146	A	1/1